

STW56NM60N

N-channel 600 V, 0.05 Ω 45 A TO-247 MDmesh™ II Power MOSFET

Preliminary data

Features

Order code	V _{DSS}	R _{DS(on)} max	Ι _D
STW56NM60N	600 V	< 0.06 Ω	45 A

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

Switching applications

Description

This device is an N-channel Power MOSFET developed using the second generation of MDmesh[™] technology. This revolutionary Power MOSFET associates a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. It is therefore suitable for the most demanding high efficiency converters.

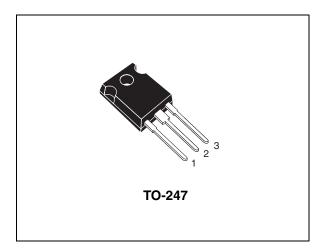


Figure 1. Internal schematic diagram

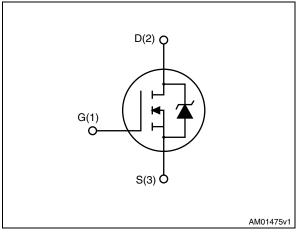


Table 1.Device summary

Order code	Marking	Package	Packaging
STW56NM60N	56NM60N	TO-247	Tube

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1

Electrical ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V _{GS} = 0)	600	V
V _{GS}	Gate-source voltage	± 25	V
Ι _D	Drain current (continuous) at $T_C = 25 \ ^{\circ}C$	45	А
Ι _D	Drain current (continuous) at $T_C = 100 \ ^{\circ}C$	28	А
I _{DM} ⁽¹⁾	Drain current (pulsed)	180	А
P _{TOT}	Total dissipation at $T_C = 25 \ ^{\circ}C$	300	W
I _{AS}	Avalanche current, repetitive or not- repetitive (pulse width limited by Tj max)	TBD	A
E _{AS}	Single pulse avalanche energy (starting T _J =25 °C, I _D =I _{AS} , V _{DD} =50 V)	TBD	mJ
dv/dt ⁽²⁾	Peak diode recovery voltage slope	15	V/ns
T _{stg}	Storage temperature	- 55 to 150	°C
Тj	Max. operating junction temperature	150	°C

Table 2. Absolute maximum ratings

1. Pulse width limited by safe operating area

2. I_{SD} \leq 11 A, di/dt \leq 400 A/µs, V_{DS} peak \leq V_{(BR)DSS}, VDD = 80% V_{(BR)DSS}.

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.42	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max	50	°C/W
T _I Maximum lead temperature for soldering purpose		300	°C



2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

	On/on states					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage (V _{GS} = 0)	I _D = 1 mA,	600			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = 600 V V _{DS} = 600 V, T _C = 125 °C			1 100	μΑ μΑ
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	$V_{GS} = \pm 20 V$			100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 22.5 A		0.05	0.06	Ω

Table 4. On/off states

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 50 V, f = 1 MHz, V _{GS} = 0	-	4800 320 4.5	-	pF pF pF
C _{oss eq.} ⁽¹⁾	Equivalent output capacitance	$V_{GS} = 0, V_{DS} = 0$ to 480 V	-	TBD	-	pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 480 \text{ V}, I_D = 45 \text{ A},$ $V_{GS} = 10 \text{ V},$ <i>(see Figure 3)</i>	-	150 TBD TBD	-	nC nC nC

1. $C_{oss eq}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}



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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 300 \text{ V}, I_D = 22 \text{ A}$ $R_G = 4.7 \Omega V_{GS} = 10 \text{ V}$ (see Figure 2)	-	TBD TBD TBD TBD	-	ns ns ns ns

Table 6.Switching times

Table 7.Source drain diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD} I _{SDM} ⁽¹⁾	Source-drain current Source-drain current (pulsed)		-		45 180	A A
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 45 \text{ A}, V_{GS} = 0$	-		1.6	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 45 A, di/dt = 100 A/µs V _{DD} = 100 V (see Figure 4)	-	TBD TBD TBD		ns μC Α
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 45 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$ $V_{DD} = 100 \text{ V}, \text{ T}_{j} = 150 ^{\circ}\text{C}$ (see Figure 4)	-	TBD TBD TBD		ns μC Α

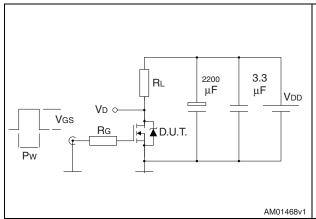
1. Pulse width limited by safe operating area

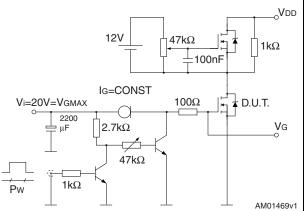
2. Pulsed: pulse duration = 300 μ s, duty cycle 1.5%



3 Test circuits

Figure 2. Switching times test circuit for resistive load



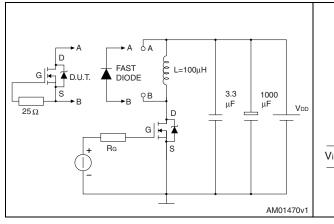


Gate charge test circuit

Figure 3.

Figure 4. Test circuit for inductive load I switching and diode recovery times





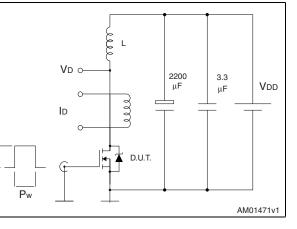
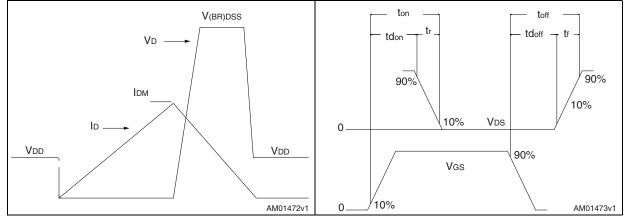




Figure 7. Switching time waveform





4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



Dim.		mm	
Dim.	Min.	Тур.	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
с	0.40		0.80
D	19.85		20.15
E	15.45		15.75
е		5.45	
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S		5.50	

Table 8. TO-247 mechanical data



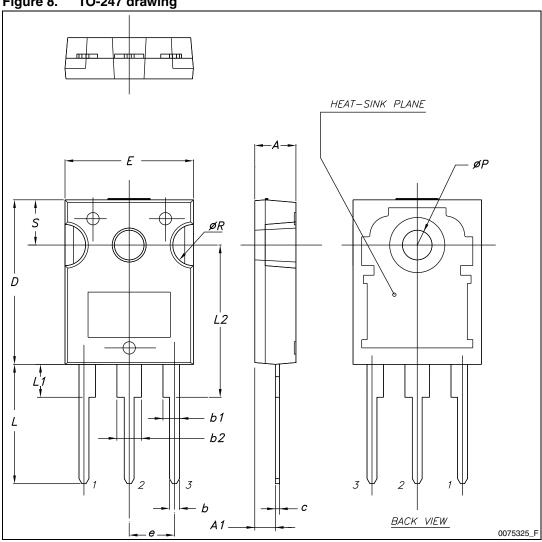


Figure 8. TO-247 drawing



5 Revision history

Table 9.Document revision history

Date	Revision	Changes
30-Nov-2010	1	First release
18-Jul-2011	2	<i>Section 4: Package mechanical data</i> has been updated. Minor text changes.



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